


Date: 4/16/2021

Material Number: SI8271GA-IS

Pkg Config.: PK1212

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	34.66	Carbon Black	1333-86-4	0.300	0.104	3000	0.1493	1493
			Cresol Novalac	29690-82-2	1.700	0.589	17000	0.8460	8460
			Epoxy Resin (Proprietary)	Proprietary	6.000	2.080	60000	2.9858	29858
			Phenol Resin (Proprietary)	Proprietary	6.000	2.080	60000	2.9858	29858
			Silicon Dioxide	60676-86-0	86.000	29.808	860000	42.7963	427963
2	Die Attach Epoxy	0.91	Acrylate monomer 10089	TS ref# 10089	5.000	0.046	50000	0.0653	653
			Acrylate monomer 10123	TS ref# 10123	5.000	0.046	50000	0.0653	653
			Acrylate monomer 10283	TS ref# 10283	5.000	0.046	50000	0.0653	653
			Bismaleimide monomer	TS ref# 10049	5.000	0.046	50000	0.0653	653
			Silver	7440-22-4	80.000	0.728	800000	1.0452	10452
3	Bond Wire	0.10	Gold	7440-57-5	99.000	0.099	990000	0.1421	1421
			Palladium	7440-05-3	1.000	0.001	10000	0.0014	14
4	Leadframe	33.50	Copper	7440-50-8	96.190	32.224	961900	46.2651	462651
			Gold	7440-57-5	0.020	0.007	200	0.0096	96
			Iron	7439-89-6	2.250	0.754	22500	1.0822	10822
			Nickel	7440-02-0	1.250	0.419	12500	0.6012	6012
			Palladium	7440-05-3	0.050	0.017	500	0.0240	240
			Phosphorous	7723-14-0	0.100	0.034	1000	0.0481	481
			Silver	7440-22-4	0.020	0.007	200	0.0096	96
			Zinc	7440-66-6	0.120	0.040	1200	0.0577	577
5	Die	0.24	Aluminum	7429-90-5	0.163	0.000	1630	0.0006	6
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.239	997260	0.3436	3436
			Tungsten	7440-33-7	0.110	0.000	1100	0.0004	4
6	Die	0.24	Aluminum	7429-90-5	0.163	0.000	1630	0.0006	6
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.239	997260	0.3436	3436
			Tungsten	7440-33-7	0.110	0.000	1100	0.0004	4
	Total Unit Weight =	69.65				69.65		100.0000	1000000